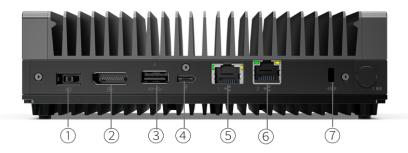
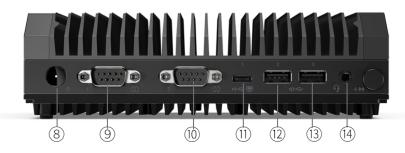


# **OVERVIEW**





1. Power connector	8. Power button
2. HDMI (for i3) / DisplayPort (for i5)	9. Serial
3. USB 3.2 Gen 2	10. Serial
4. Thunderbolt 4	11. USB-C 3.2 Gen 2
5. Ethernet (RJ-45)	12. USB 3.2 Gen 2
6. Ethernet (RJ-45)	13. USB 3.2 Gen 2
7. Kensington Security Slot	14. Headphone / microphone combo jack (3.5mm)



## **PERFORMANCE**

### **Processor**

### **Processor Family**

11th Generation Intel® Core™ i3 / i5 Processor

### Processor\*\*[1]

Processor Name	Cores	Threads	Base Frequency	Cache	Memory Support	Processor Graphics
Core i3-1115GRE	2	4	1.7GHz	6MB	DDR4-3200	Intel UHD Graphics
Core i5-1145GRE	4	8	1.1GHz	8MB	DDR4-3200	Intel Iris® Xe Graphics

#### Notes:

1. Intel Turbo Boost is disabled on SE30. The maximum TDP of CPU is 12W. The max frequency is not obtainable at high work levels, the CPU will adjust the frequency to obtain the maximum TDP allowed.

## **Operating System**

### Operating System\*\*

- Windows® 10 IoT Enterprise LTSC 2021
- Ubuntu Core
- Ubuntu Server
- No operating system

## **Graphics**

### Graphics\*\*

	Graphics	Туре	Memory	Boost Clock	TGP	Connector	Max Resolution	Key Features	Remark
- 1	Intel UHD graphics	Integrated	Shared	-	-	1x HDMI® 1.4b, 1x USB-C®, 1x Thunderbolt™	3840x2160@30Hz(HDMI), 3840x2160@60Hz(USB-C), 3840x2160@60Hz(Thunderbolt)	DirectX® 12	-
	Intel Iris Xe Graphics	Integrated	Shared	-	-	1x DP 1.4a, 1x USB-C, 1x Thunderbolt	3840x2160@60Hz(DP), 3840x2160@60Hz(USB-C), 3840x2160@60Hz(Thunderbolt)	DirectX 12	-

## **Monitor Support**

### **Monitor Support**

Supports up to 3 independent displays via onboard ports (i3 models supports HDMI, USB-C, and Thunderbolt; i5 models supports DisplayPort $^{\text{\tiny{TM}}}$ , USB-C, and Thunderbolt)

## **Chipset**

### Chipset

Intel SoC (System on Chip) platform

## **Memory**

### **Max Memory**

- 8GB soldered memory, not upgradable
- 16GB soldered memory, not upgradable

#### **Memory Slots**

Memory soldered to systemboard, no slots, dual-channel

### **Memory Type**

DDR4-3200

## Memory Protection[1]

IB-ECC

### Notes:

1. IB-ECC needs to be enabled in BIOS



## **Storage**

### Storage Support[1]

Up to two drives, 2x M.2 2230 SSD

- M.2 2230 SSD up to 1TB each
- RAID 0/1 support

#### Storage Type\*\*\*

Disk Type	Interface	Security
M.2 2230 SSD	PCIe® NVMe®, PCIe 3.0	-
M.2 2230 SSD	PCIe NVMe, PCIe 3.0	Opal

#### RAID<sup>[2]</sup>

RAID 0/1 support

## Notes:

- 1. The storage capacity supported is based on the test results with current Lenovo® storage offerings. The system may support larger storage as the technology develops.
- 2. RAID preset is available via special bid, limited to the models with Windows 10 IoT Enterprise.

## **Power Supply**

### **Power Supply**

Power	Туре	Efficiency	Key Features
65W	Adapter	89%	Autosensing
No power supply	-	-	-

### **DESIGN**

## **Input Device**

## Keyboard\*\*

- Lenovo Calliope Keyboard (USB connector), black
- · Lenovo Calliope Wireless Keyboard, black
- · Lenovo Traditional Keyboard (USB connector), black
- · No keyboard

#### Mouse\*\*

- Lenovo Calliope Mouse (USB connector), black
- Lenovo Fingerprint Mouse (USB connector), black
- · No mouse

### **Mechanical**

### **Dimensions (WxDxH)**

Models	Dimensions
IO box	178 x 88 x 25.6 mm (7.01 x 3.46 x 1.00 inches)
ThinkEdge SE30	179 x 88 x 51.5 mm (7.05 x 3.46 x 2.03 inches)

### Weight

Models	Weight
IO box	Around 0.499 kg (1.10 lbs)
ThinkEdge SE30	Around 1.02 kg (2.25 lbs)

### **Case Color**

Black

#### IO Box[1]

- ThinkEdge SE30 IO box: 2x serial (RS232 / RS422 / RS485) and 2x gigabit Ethernet (RJ-45) on front, 1x DIO (4DI / 4DO), USB-C 3.2 Gen 1 (connect to SE30), and DC-in connector (9V 36V) on rear
- No IO box



### Mounting\*\*

- VESA mount bracket kit with adapter holder, supports VESA mount 75mm and 100mm
- VESA mount bracket kit, supports VESA mount 75mm and 100mm
- · DIN rail mount bracket kit
- 7 hook
- None

#### Notes:

1. For more details, please go to https://pcsupport.lenovo.com

### CONNECTIVITY

### **Network**

#### **Ethernet**

1x gigabit Ethernet (Realtek® RTL8111KI-CG) and 1x 2.5 gigabit Ethernet (Intel I225-IT), 2x RJ-45, supports Wake-on-LAN

#### WLAN + Bluetooth®\*\*[1]

- Intel Wireless-AC 9260, 802.11ac Dual Band 2x2 Wi-Fi® + Bluetooth 5.0, Intel vPro® technology support, M.2 card
- Intel Wireless-AC 9260, 802.11ac Dual Band 2x2 Wi-Fi + Bluetooth 5.0, M.2 card
- No WLAN and Bluetooth

#### WWAN\*\*

- Quectel EM160R-GL, Qualcomm<sup>®</sup> Snapdragon™ X24 LTE Modem, CAT16, M.2 card
- Qualcomm Snapdragon X55 5G Modem-RF System, Sub-6 GHz, M.2 card
- No support

#### Notes:

1. Bluetooth 5.2 is hardware ready but may run at a lower version due to OS limitation

### Ports<sup>[1]</sup>

### **Front Ports**

- 2x USB 3.2 Gen 2
- 1x USB-C 3.2 Gen 2 (support data transfer and display)
- 1x headphone / microphone combo jack (3.5mm)
- 2x serial (RS232 / RS422 / RS485, BIOS selectable)

### **Optional Front Ports\*\*\***

- 2x gigabit Ethernet (RJ-45) on SE30 IO box
- 2x serial (RS232 / RS422 / RS485, SDK selectable) on SE30 IO box

### Rear Ports[2]

- 1x USB 3.2 Gen 2
- 1x HDMI 1.4b (for i3 models)
- 1x DisplayPort 1.4a (for i5 models)
- 1x Thunderbolt 4 / USB4® 40Gbps (support data transfer, Power Delivery 5V@3A, and display)
- 2x Ethernet (RJ-45)
- 1x power connector

#### Optional Rear Ports\*\*\*

- 1x USB-C 3.2 Gen 1 on SE30 IO box, connect to SE30
- 1x DC-in 3pin Phoenix connector on SE30 IO box
- 1x DIO (4DI / 4DO) on SE30 IO box

#### Notes:

1. The transfer speed of following ports will vary and, depending on many factors, such as the processing speed of the host device, file attributes and other factors related to system configuration and your operating environment, will be slower than theoretical speed. USB 2.0: 480 Mbit/s;

USB 3.2 Gen 1 (SuperSpeed USB 5Gbps, formerly USB 3.0 / USB 3.1 Gen 1): 5 Gbit/s;

USB 3.2 Gen 2 (SuperSpeed USB 10Gbps, formerly USB 3.1 Gen 2): 10 Gbit/s;

USB 3.2 Gen 2x2 (SuperSpeed USB 20Gbps): 20 Gbit/s;

Thunderbolt 3/4: 40 Gbit/s

2. If IO box gets power supply from ThinkEdge SE30, need to connect USB-C (on IO box) with Thunderbolt 4 port (on SE30)

### **Monitor Cable**



#### Monitor Cable\*\*\*

- USB-C to DP dongle
- USB-C to HDMI dongle
- USB-C to VGA dongle
- DP to VGA dongle
- DP to Dual DP (MST) dongle
- DP to Dual DP (SST) dongle
- DP to HDMI 1.4 dongle
- No monitor cable

## **SECURITY & PRIVACY**

## **Security**

## **Security Chip**

Discrete TPM 2.0, TCG certified

### **Physical Locks**

Kensington® Security Slot™, 3 x 7 mm

#### **Chassis Intrusion Switch**

Chassis intrusion switch

### **BIOS Security**

- Self-healing BIOS
- Self-healing BIOS (EC-based)

## **MANAGEABILITY**

## **System Management**

### **System Management**

- Intel vPro with Intel AMT 15
- Non-vPro

## **SERVICE**

# Warranty<sup>[1]</sup>

### Base Warranty\*\*

- 1-year courier or carry-in service
- 1-year limited onsite service
- 3-year limited onsite service
- No base warranty

### Notes:

1. The warranty upgrades may be bundled with some models, please check the "Included upgrade" column in the specific model's configurations. For more service extensions, please go to <a href="https://smartfind.lenovo.com/">https://smartfind.lenovo.com/</a>. To learn more details of warranty policy, please access <a href="https://pcsupport.lenovo.com/warranty">https://pcsupport.lenovo.com/warranty</a>.

## **ENVIRONMENTAL**

## Operating Environment<sup>[1]</sup>

## Temperature

- Operating: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -20°C (-4°F) to 60°C (140°F) with 0.7 m/s air flow
- Storage: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -40°C (-40°F) to 85°C (185°F)

#### Humidity

- Relative humidity storage: IEC 60068-2-66 Damp heat, steady state 90%@60°C
- Relative humidity operating: IEC 60068-2-66 Damp heat, steady state 95%@40°C non-condensing

### **Shock Protection**



IEC 60068-2-27, shock, operating, 30G / 11ms, half sine

#### **Vibration Protection**

IEC 60068-2-64, Vibration, Operating, 3Grms, random, 5 ~ 500Hz, 1hr/axis

Notes:

1. The temperature spec is not applicable for hardware accessories.

### CERTIFICATIONS

### **Green Certifications**

## Green Certifications

- ErP Lot 6
- Low Halogen
- · RoHS compliant
- REACH
- PCF
- TED (ECO-declaration)
- WEEE

## **Other Certifications**

#### **EMC**

- EMC CE / FCC Class B
- BSMI
- CCC

#### Safety

- UL(ETL)
- BSMI
- CB
- CCC
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